

# Product Change Notification

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**Product Change Notification Number: GC192801**

**Date 24 July 2019**

**Title: FPBGA Encapsulation site change for data converters**

**Product Identification:**

**EV10DS130ACZPY      EV12DS130ACZPY**  
**EV10DS130AVZPY      EV12DS130AVZPY**

See also [https://www.teledyne-e2v.com/shared/content/resources/File/documents/Semiconductors/PCN\\_EOLs/GE184051\\_EOL.pdf](https://www.teledyne-e2v.com/shared/content/resources/File/documents/Semiconductors/PCN_EOLs/GE184051_EOL.pdf)

**Reason for Change:**

- |   |  |  |
|---|--|--|
| <input type="checkbox"/> Design           | <input type="checkbox"/> wafer Processing  | <input type="checkbox"/> wafer Materials                   |
| <input type="checkbox"/> Logistics        | <input type="checkbox"/> Other             | <input checked="" type="checkbox"/> Manufacturing Location |
| <input type="checkbox"/> Process Material | <input type="checkbox"/> Assembly Material | <input type="checkbox"/> Quality/Reliability               |
|   | <input type="checkbox"/> Product Marking   |  |

**Change Description:**

Change of FPBGA196 subcontractor given the previous production site end of life notice.

**Anticipated Impact of Product Change (Form, Fit Function):**

No changes will be seen in form, fit, or function. No impact to existing datasheet

**Identification Method to Distinguish Change:** Based on the Date Code value.

All Date Code equal or greater than 1925 reflects the new assembly location.

P/N reference and marking information remain the same.

**Qualification Data:**       available     will be available in week 50/2019       not applicable

**Samples:**       prototypes available       will be available       not applicable

**Quantifiable Impact on Quality & Reliability:** *None expected.*

**Implementation Date\*:**      Estimated January-2020

First Shipment with packaging originated from the new location could start from January 2020 onwards.

Exact dates might vary depending from customers' orders mix, backlog execution on the above listed product and inventory depletion

*\*The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, e2v semiconductors will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.*

**Teledyne e2v semiconductors contact:**

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Please contact your local Teledyne-e2v sales representative for any commercial inquiry.

**APPROVAL by TRB**

Teledyne e2v semiconductors will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

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